

N-Channel Enhancement Mode Power MOSFET

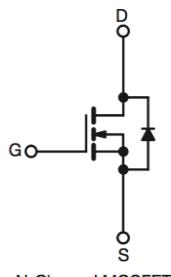
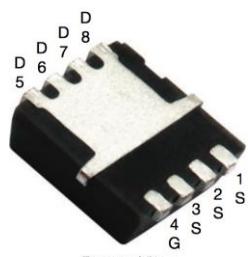
● Features

$V_{DS} = 30V$,
 $I_D = 12A$
 $R_{DS(ON)} @ V_{GS} = 10V$, TYP 8.5mΩ
 $R_{DS(ON)} @ V_{GS} = 4.5V$, TYP 13mΩ

● General Description

- DC/DC Converters in Computing , servers, POL
- Isolated DC/DC Converters in Telecom and Industrial

● Pin Configurations



PDFN3*3-8L

● Absolute Maximum Ratings @ $T_A=25^\circ C$ unless otherwise noted

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V_{DSS}	30	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current (Continuous) *ACD	$T_A=25^\circ C$	I_D	12	A
	$T_A=70^\circ C$		9.4	
Drain Current (Pulse) *B		I_{DM}	48	A
Power Dissipation	$T_A=25^\circ C$	P_D	20.5	W
Operating Temperature/ Storage Temperature		T_J/T_{STG}	-55~150	°C

● Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R_{thJA}	47	60	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	8	10	

● **Electrical Characteristics @ $T_A=25^\circ C$** unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30 V, V_{GS} = 0V$	--	--	1	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_{DS} = 250\mu A$	1	1.8	2.5	V
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	--	--	± 100	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	--	8.5	11	$m\Omega$
	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 10A$	--	13	17	$m\Omega$
Diode Forward Voltage	V_{SD}	$I_{SD} = 1A, V_{GS} = 0V$	--	--	1	V
Diode Forward Current	I_S	$T_C = 25^\circ C$	--	--	10	A
Switching						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=15V, I_D=12A$	--	9	--	nC
Gate-Source Charge	Q_{gs}		--	1.4	--	nC
Gate-Drain Charge	Q_{gd}		--	1.9	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V, R_L=1.25\Omega$ $V_{GEN}=10V, R_g=3\Omega$	--	5	--	ns
Turn-on Rise Time	t_r		--	2.5	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	17.5	--	ns
Turn-Off Fall Time	t_f		--	2.5	--	ns
Dynamic						
Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, f=1.0MHz$	--	600	--	pF
Output Capacitance	C_{oss}		--	230	--	pF
Reverse Transfer Capacitance	C_{rss}		--	30	--	pF

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the $t \leq 10s$ junction to ambient thermal resistance rating.

D. The maximum current rating is package limited.

- Typical Performance Characteristics (($T_J = 25^\circ\text{C}$, unless otherwise noted))

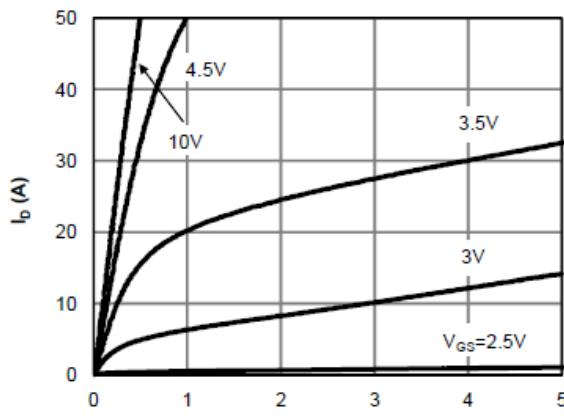


Figure 1: On-Region Characteristics

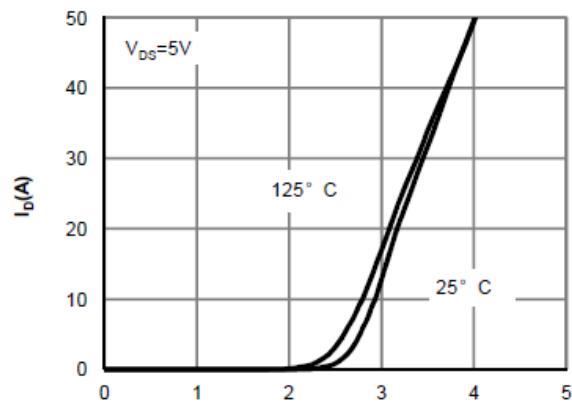


Figure 2: Transfer Characteristics

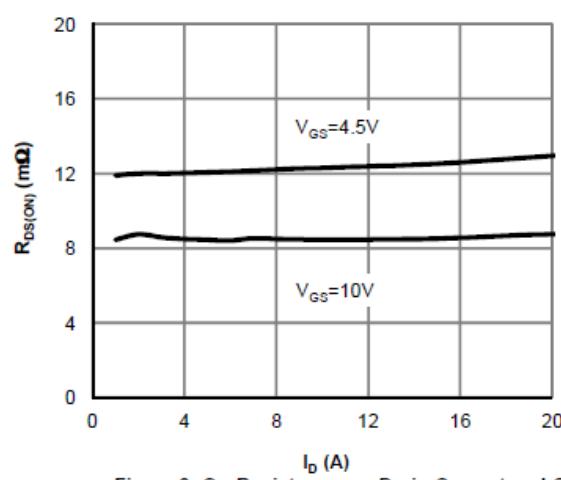


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

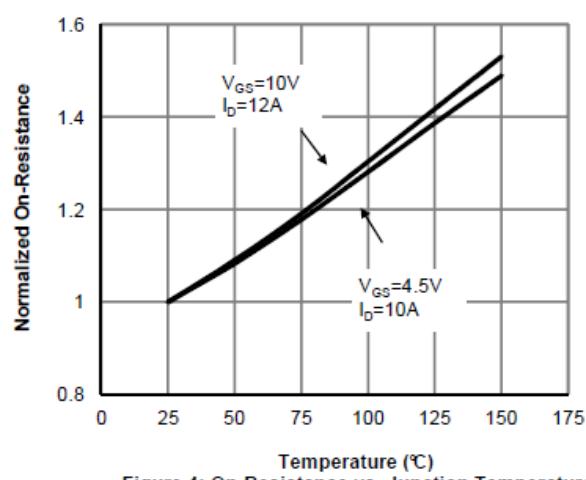


Figure 4: On-Resistance vs. Junction Temperature

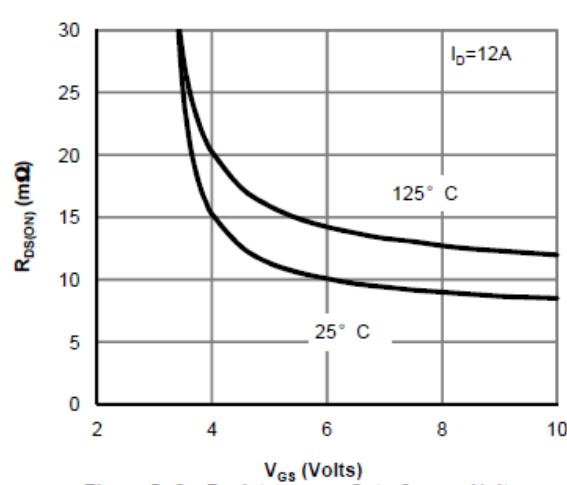


Figure 5: On-Resistance vs. Gate-Source Voltage

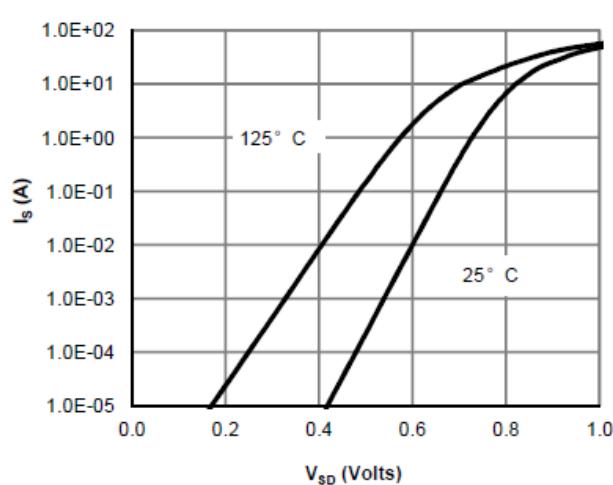
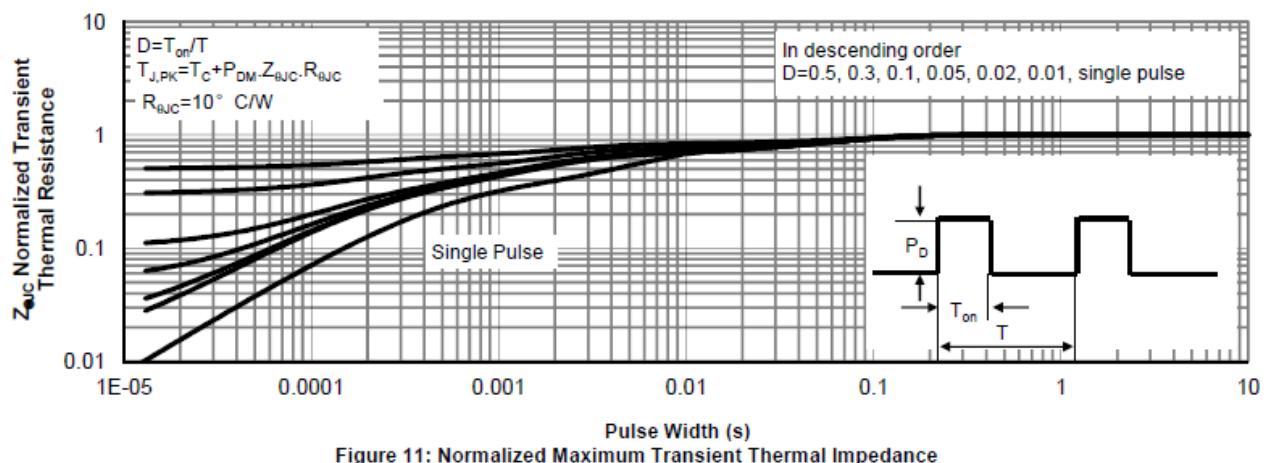
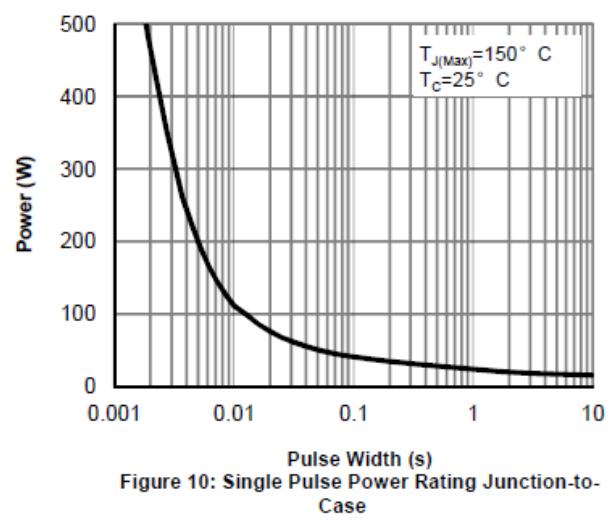
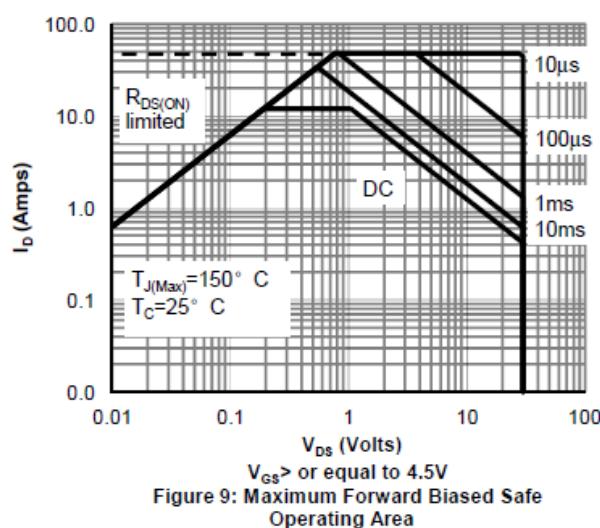
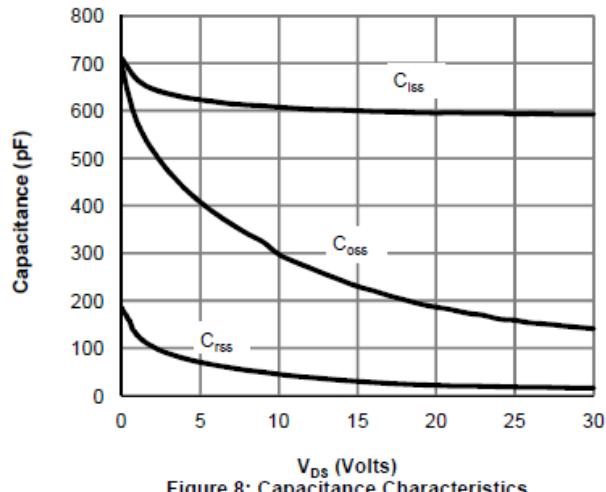
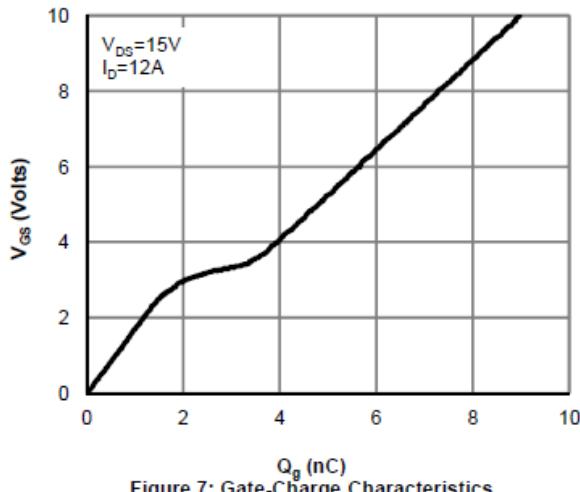


Figure 6: Body-Diode Characteristics



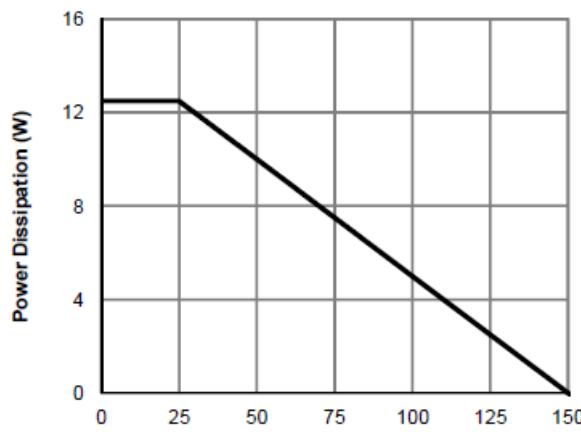


Figure 12: Power De-rating

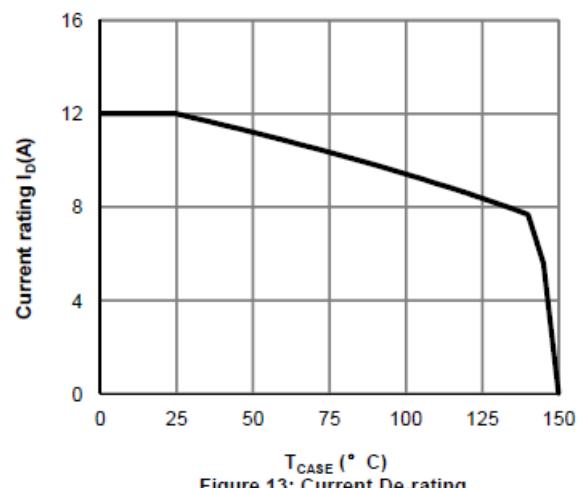


Figure 13: Current De-rating

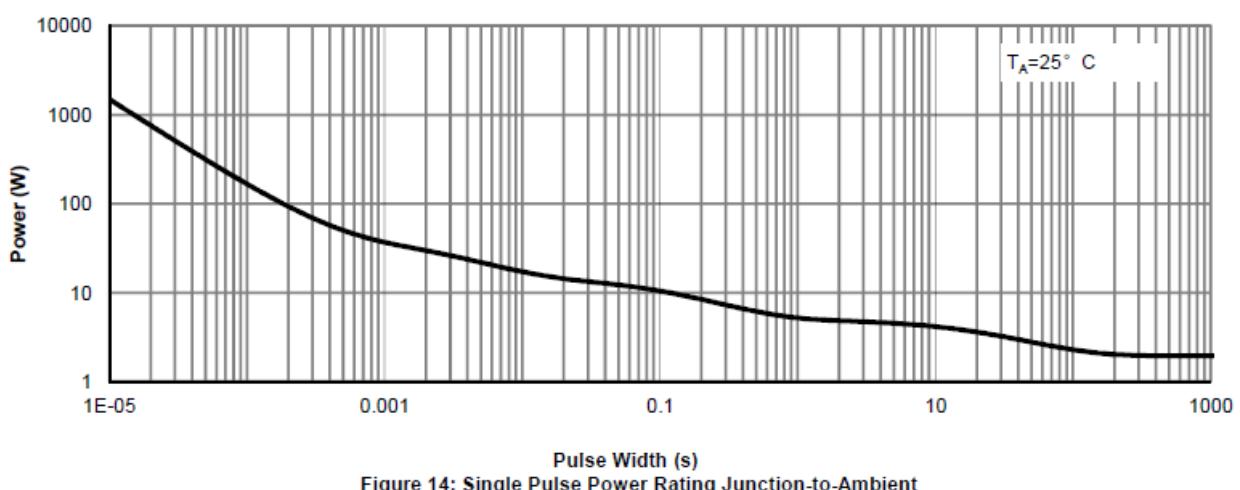


Figure 14: Single Pulse Power Rating Junction-to-Ambient

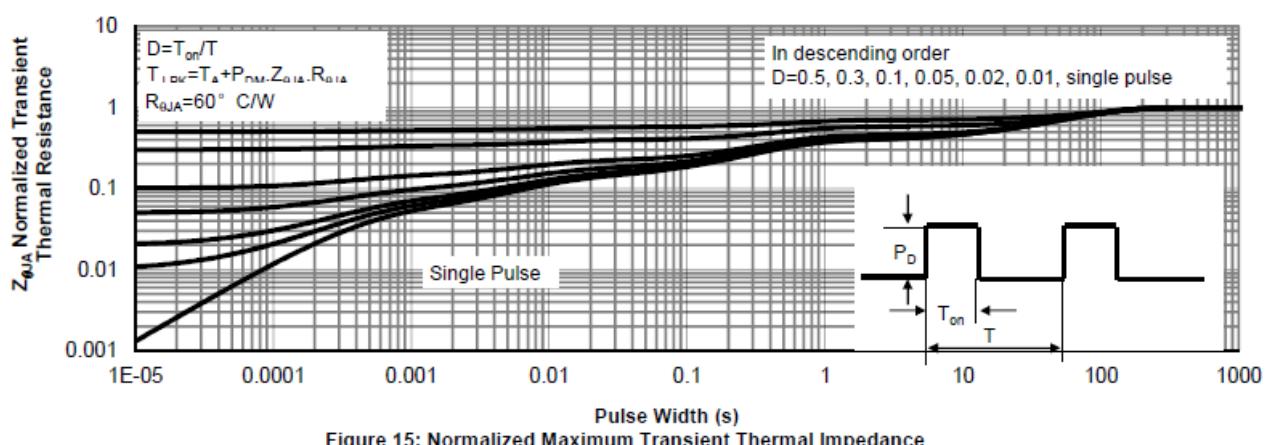
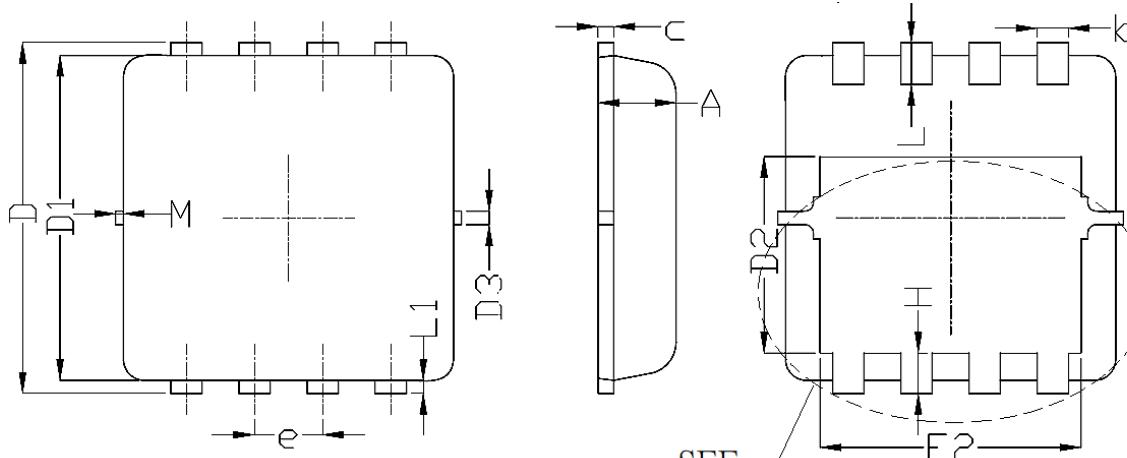
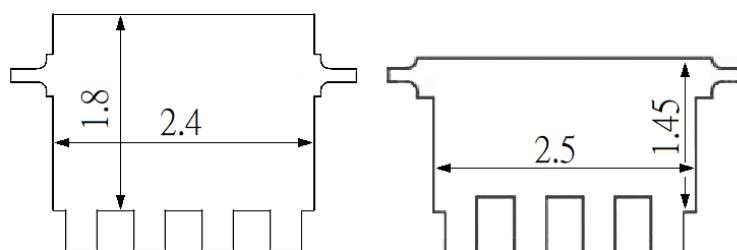
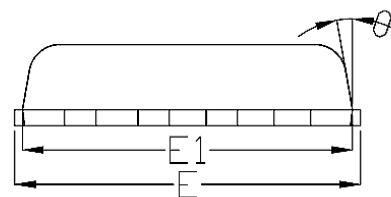


Figure 15: Normalized Maximum Transient Thermal Impedance

- Package Information



SEE
DETAIL



OPTION 1

OPTION 2

DETAIL

SYMBOL	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	0.7	0.775	0.85
b	0.25	0.3	0.35
c	0.1	0.15	0.25
D	3.15	3.3	3.4
D1	2.95	3.1	3.2
D2	1.7	1.8	1.93
D3		0.13	
E	3.05	3.25	3.35
E1	2.95	3.15	3.2
E2	2.3	2.4	2.55
e	0.65 BSC		
H	0.33	0.43	0.53
L	0.3	0.4	0.5
L1	0.08	0.13	0.18
θ	-	10°	12°
M	-	-	0.15